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JUN 30 2003

TECHNOLOGY CENTER 2800

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450
Attention:
Art Unit: 2813

Re: **-DIELECTRIC RECESS FOR WAFER-TO-WAFER AND DIE-TO-DIE BONDING
 AND METHOD OF FABRICATING THE SAME—**
 U.S. Application No: 10/066,645
Attorney Docket No: 219.40606X00

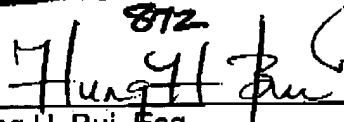
**SUBMISSION OF AMENDMENT PREPARED IN RESPONSE TO
 OFFICE ACTION (Paper No. 7) DATED ON June 10, 2003**

Sir:

Applicant hereby submits the attached Amendment (12 pages), in the above-identified application.

CERTIFICATE OF TRANSMISSION:

I hereby certify that the attached "Amendment" (12 pgs) prepared in response to the first Office Action (Paper No. 7), is being formally filed in the USPTO via Group Art Unit **2800** **2813**, Examiner Nema O. Berezny, Facsimile No. 703-367-9318 on **June 30, 2003**.

812

 Hung H. Bui, Esq.

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219.40606X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Scot A. KELLAR et al.

Serial No.: 10/066,645

Filed: February 6, 2002

For: DIELECTRIC RECESS FOR WAFER-TO-WAFER AND DIE-TO-DIE BONDING AND METHOD OF FABRICATING THE SAME

Group: 2811

Examiner: Berezny, NEMA

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JUN 30 2003

TECHNOLOGY CENTER 2800

AMENDMENTCommissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 30, 2003

Sir:

In response to the Office action (Paper No. 7) dated on June 10, 2003, entry of the following amendments to the above-identified application, reconsideration and reexamination, are respectfully requested.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.

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